

Title (en)
METHOD FOR INTEGRATING AN ELECTRONIC COMPONENT INTO A PRINTED CIRCUIT BOARD

Title (de)
VERFAHREN ZUR INTEGRATION EINES ELEKTRONISCHEN BAUTEILS IN EINE LEITERPLATTE

Title (fr)
PROCÉDÉ D'INTÉGRATION D'UN COMPOSANT ÉLECTRONIQUE DANS UNE CARTE IMPRIMÉE

Publication
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Application
EP 09756396 A 20091028

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Abstract (en)
[origin: WO2010048654A1] The invention relates to a method for integrating an electronic component into a printed circuit board, said method comprising the following steps: a layer of a printed circuit board is used to support the electronic component (4); holes (3) corresponding to the contacts (6) of the electronic component (4) are formed in the layer (1); an adhesive (5) is applied to the layer (1) supporting the electronic component (4); the electronic component (4) is fixed to the layer (1) with the contacts (6) oriented towards the layer (1) and the holes (3); adhesive (5) possibly in the region of the holes or perforations (3) is removed, especially by the application of a laser beam (9); and an electroconductive layer (10) is formed for contacting the contacts (6) of the electronic component (4) on the surface of the layer (1), facing away from the component (4). According to said method, in order to remove the adhesive (5) from the holes or perforations (3), a laser beam (9) with dimensions or a diameter measuring more than the internal width of the holes or perforations is used, enabling a simple, rapid and reliable removal of adhesive (5) from the holes (3) corresponding to the contacts (6) of the component (4) to be integrated.

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